ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN22334X
Issue Date: 10 September 2018

Title of Change:	Qualification of OSPI Tarlac Site for assembly of UQFN10 NL3S2223MUTBG.
Proposed first ship date:	17 December 2018 or earlier upon customer approval
Contact information:	Contact your local ON Semiconductor Sales Office or <guy.rahamim@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < phine.guevarra@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>
Change Part Identification:	Affected products will be identified with date code.
Change Category:	☐ Wafer Fab Change ☑ Assembly Change ☐ Test Change ☐ Other ________________

Change Sub-Category(s):

☑ Manufacturing Site Addition
☐ Manufacturing Site Transfer
☑ Manufacturing Process Change
☑ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ________________________________

Sites Affected:	ON Semiconductor Sites: ON Tarlac City, Philippines	External Foundry/Subcon Sites: None

Description and Purpose:

This is a Final Process Change Notification to inform customers that the DPDT switch device for High-Speed USB 2.0 applications - NL3S2223MUTBG - which is currently being manufactured in subcon sites Amkor Philippines and UTAC Thailand, is now also qualified for assembly in OSPI Tarlac site.

There will be no change in the electrical characteristics of the involved part numbers.

	Before Change Description	**After Change Description**
Mold Compound	G700Y	G760

There is no product marking change as a result of this change.

Reliability Data Summary:

QV DEVICE NAME: NL3S2223MUTBG
RMS: S42761/S43949
PACKAGE: uQFN 10

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/240
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/240
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/240
HAST	JESD22-A110	110°C, 85% RH, 18.8psig, bias	264 hrs	0/240
uHAST	JESD22-A118	110°C, 85% RH, 18.8psig, unbiased	264 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @260°C		0/720
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 10 sec		0/45
PD	JESD22-B100	Cpk >1.67		0/30
ED	AEC Q100-009	Cpk >1.67		0/90

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Part Number	Qualification Vehicle
NL3S2223MUTBG	NL3S2223MUTBG